# SimpleLink<sup>™</sup> *Bluetooth*<sup>®</sup> Smart CC2640 Wireless Microcontroller



The SimpleLink™ *Bluetooth*® Smart CC2640, a member of the SimpleLink



tion on smaller coin cells. It is also the most integrated solution available with a complete system design that will fit on your fingertip.

#### **Overview**

The CC2640 is designed with low-power Bluetooth Smart applications in mind due to its very low sleep, active, RF and average current. Compared to older MCUs, the ARM® Cortex®-M3 processor requires less processing time for application and stack processing and the current consumption per MIPS is among the lowest in the industry. The CC2640 uses

TI's unique sensor controller to interface external digital and analog circuitry in a low-power manner to achieve even longer battery life. All of these features are integrated in a 4×4 QFN package suitable for smaller end products due to less external circuitry. Designing with this device is made easy with TI's comprehensive support platforms, including TI's BLE-Stack software development kit, the Bluetooth Smart SensorTag, development kit and evaluation modules, as well as TI's E2E™ community.

#### Key features of the CC2640

## The lowest power:

Multi-year operation on a coin cell: ARM® Cortex®-M3 MCU, radio, sleep current, and unique sensor controller

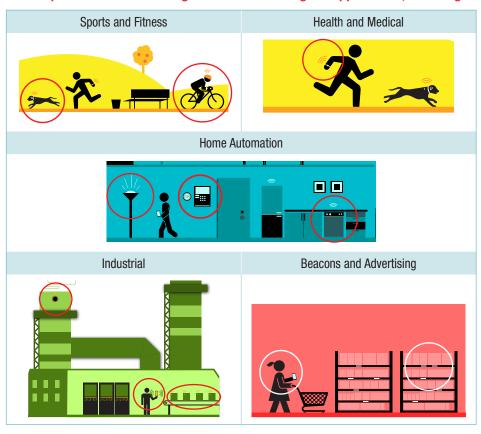
## • The most integrated:

Complete solution in a fingertip size: Single-chip, Flash-based 4×4-mm QFN

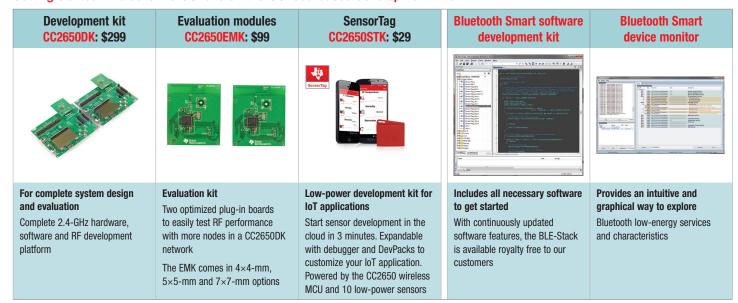
# • Easiest to design with:

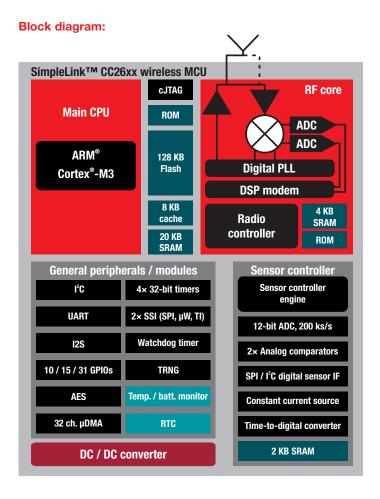
Comprehensive design support: Complete software stack, wiki guides, dynamics design kits, lowcost tools and software starting points

### The SimpleLink CC2640 is designed for a broad range of applications, including:



# Getting started: Evaluate the CC2640 on the CC2650-based development kits





For more information on the SimpleLink ultra-low power wireless MCU platform, please visit www.ti.com/simplelinkulp

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